

MATERIAL DATA SHEET



SMD Diodes Specialist

Material #	CXXC Series	
Product Line	SMC (DO-214AB)	
Date	2008/8/8	
Rev. date	A	

No.	Construction element	Material group	Material weight (mg)	Material	CAS if applicable	Average mass (%)	Sum(%)	Traces
1	Die Chip	Silicon chip	2.34	Silicon	7440-21-3	>99%	0.0102	
				other	-	<1%		
2	Solder	Pb/Sn/Ag	2.85	Pb	7439-92-1	92.50%	0.0124	
				Sn	7440-31-5	5%		
				Ag	7440-22-4	2.50%		
3	Mold Compound	Epoxy Resin	154.71	Silica (SiO2)	14808-60-7	60-90%	0.67	
				Epoxy resin	29690-82-2	10-30%		
				Phenolic resin	9003-35-4	5-20%		
				Antimony trioxide	1309-64-4	0-5%		
				Brominated epoxy resin	40039-93-8	0-5%		
				Carbon Black	1333-86-4	0-1%		
4	Plating	Plating of Sn	1.4	Sn	7440-31-5	>97%	0.01	
				other	-	<3%		
5	Lead frame	Cu	68.3	Cu	7440-50-8	>99%	0.30	
				other	-	<1%		
		Total weight	229.6					